

Sauls Wharf House Crittens Road Great Yarmouth Norfolk NR31 0AG

MC240064GD6W-BNMLW 240 x 64		LCD Module	
		Specification	
Version: 1		Date: 16/04/2018	
		Revision	
1	21/02/2010	First Issue.	
2 20/09/2012		Add Recommendable Storage.	
3	08/10/2014	Remove IC Information.	
4 02/02/2015		Modify Cable Length.	
5 25/02/2016		Modify Precaution in use of LCM and Static Electricity Test.	
6	07/02/2017	Modify VIL.	

Display F	eatures		
Resolution	240 x 64		
Appearance	White on Blue		
Logic Voltage	3.3V		
Interface	Parallel		COHS
Font Set	N/A		<b>CoHS</b>
Display Mode	C Transmissive		mphant
LC Туре	BSTN		
Module Size	180.00 x 65.00 x 12.30 mm		
Operating Temperature	-20°C ~ +70°C		
Construction	COB	Box Quantity	Weight / Display
LED Backlight	White		
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\* - For full design functionality, please use this specification in conjunction with the RA6963 specification. (Provided Separately)

Display Accessories				
Part Number	Description			
MCCBL1A20DILP -20DILS-150	20-Way Dual-in-line to Dual- in-line interconnect cable.			

Optional Variants				
Voltage				

#### **General Specification**

The Features is described as follow:

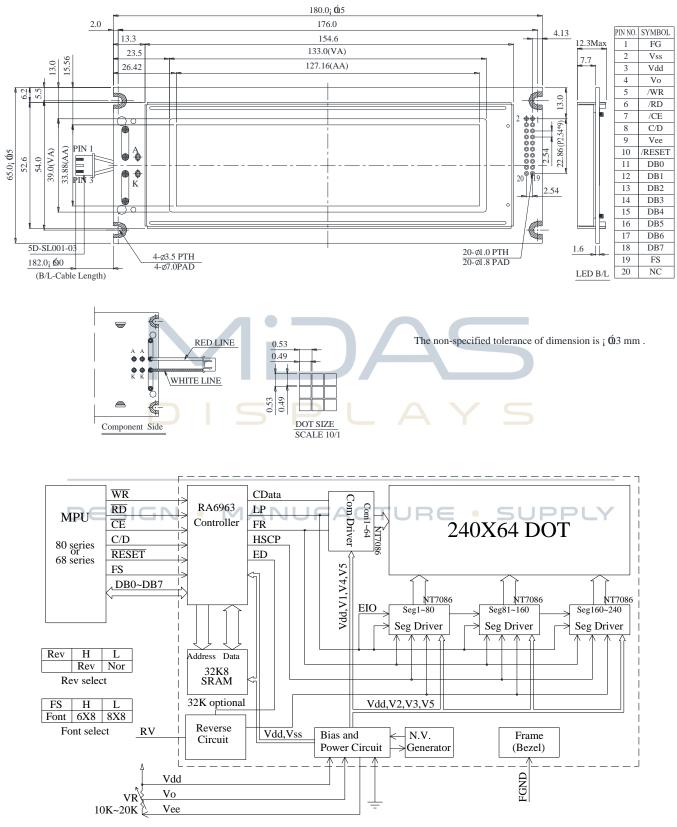
- Module dimension: 180.0 x 65.0 x 12.3 (max.) mm
- View area: 133.0 x 39.0 mm
- Active area: 127.16 x 33.88 mm
- Number of dots: 240 x 64
- Dot size: 0.49 x 0.49 mm
- Dot pitch: 0.53 x 0.53 mm
- LCD type: STN Negative, Blue Transmissive
- Duty: 1/64
- View direction: 6 o'clock
- Backlight Type: LED White
- IC:RA6963

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# **Interface Pin Function**

Pin No.	Symbol	Level	Description
1	FG	_	Frame ground ( Connected to bezel )
2	Vss	_	GND
3	Vdd	_	Power supply
4	Vo	_	Power supply for LCD driver
5	/WR	L	Data write. Write data into RA6963 when WR = L
6	/RD	L	Data read. Read data from RA6963 when RD = L
7	/CE	L	L : Chip enable
8	C/D H / L WR=L, C/D=H : Command Write C/		WR=L, C/D=H: Command Write C/D=L: Data write
			RD=L , C/D=H : Status Read C/D=L: Data read
9	Vee		Negative voltage output
10	/RESET	H/L	H : Normal ; L : Initialize RA6963
11	DB0	H/L	Data bus line AYS
12	DB1	H/L	Data bus line
13	DB2	H/L	Data bus line
14 E	SDB3N	H/M/	Data bus line CTURE • SUPPLY
15	DB4	H/L	Data bus line
16	DB5	H/L	Data bus line
17	DB6	H/L	Data bus line
18	DB7 H/L		Data bus line
19	FS	H/L	Pins for selection of font; H : 6 * 8 , L : 8 * 8
20	NC	_	No connection

#### **Contour Drawing & Block Diagram**



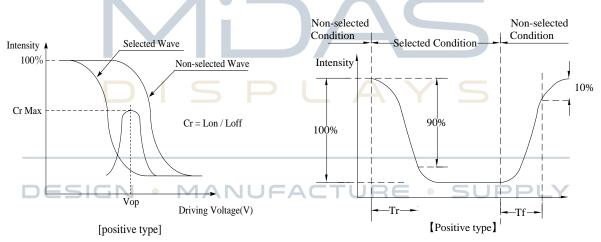
External contrast adjustment.

### **Optical Characteristics**

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	20	ψ= 180°
	θ	CR≧2	0	_	40	ψ= 0°
	θ	CR≧2	0		30	ψ= 90°
	θ	CR≧2	0	—	30	ψ= 270°
Contrast Ratio	CR	_		3		_
Response Time	T rise	_		200	300	ms
	T fall	—	_	250	350	ms

#### Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)

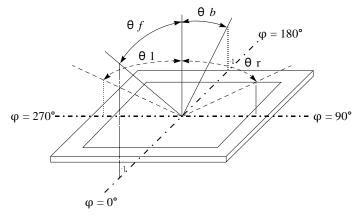


**Conditions :** 

 $\label{eq:operating voltage: Vop} \mbox{Viewing Angle}(\theta \ , \ \phi): 0^\circ \ , \ 0^\circ$ 

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

#### Definition of viewing angle( $CR \ge 2$ )



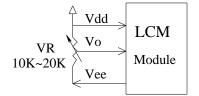
## **Absolute Maximum Ratings**

ltem	Symbol	Min	Тур	Мах	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	Тѕт	-30	_	+80	°C
Input Voltage	Vin	-0.3	_	V <sub>DD</sub> +0.3	V
Supply Voltage For Logic	Vdd-Vss	-0.3	_	+7.0	V

#### **Electrical Characteristics**

ltem		Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For	Logic	V <sub>DD</sub> -V <sub>SS</sub>		3.0	_	5.5	V
		U T	Ta=-20°C	Ą	Y _ 2	<b>1</b> 3.9	V
Supply Voltage For *Note	LCD	V <sub>DD</sub> -V <sub>0</sub>	Ta=25°C	12.1	12.5	12.9	V
		MANI	Ta=70°C	10.1	- 5		V
Input High Volt.		Vін	_	0.8Vdd	_	V <sub>DD</sub>	V
Input Low Volt.		Vil		0	_	0.15 Vdd	V
Output High Volt.		Vон		Vdd-0.3	_	V <sub>DD</sub>	V
Output Low Volt.		Vol		0	_	0.3	V
Supply Current		ldd		12	16	20	mA

\* Note: Please design the VOP adjustment circuit on customer's main board



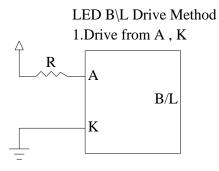
### **Backlight Information**

#### **Specification**

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT	TEST CONDITION
Supply Current	ILED	_	80	100	mA	V=3.5V
Supply Voltage	v	3.4	3.5	3.6	v	—
Reverse Voltage	VR	_	_	5	v	—
Luminance	IV	520	650		CD/M <sup>2</sup>	ILED=80mA
(Without LCD)	IV	520	050			
LED Life Time						ILED=80mA
(For Reference		1:	50K	-	Hr.	25°C,50-60%RH,
only)						(Note 1)
Color	White	5				

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



# Reliability

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°С,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°0⁄70°C 10 cycles	
	DISPLAY	Total fixed amplitude : 1.5mm	
Vibration test	Endurance test applying the vibration during transportation and using.	Vibration Frequency : 10~55Hz	3
DESIGI	N • MANUFACTURE •	One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times	

#### Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

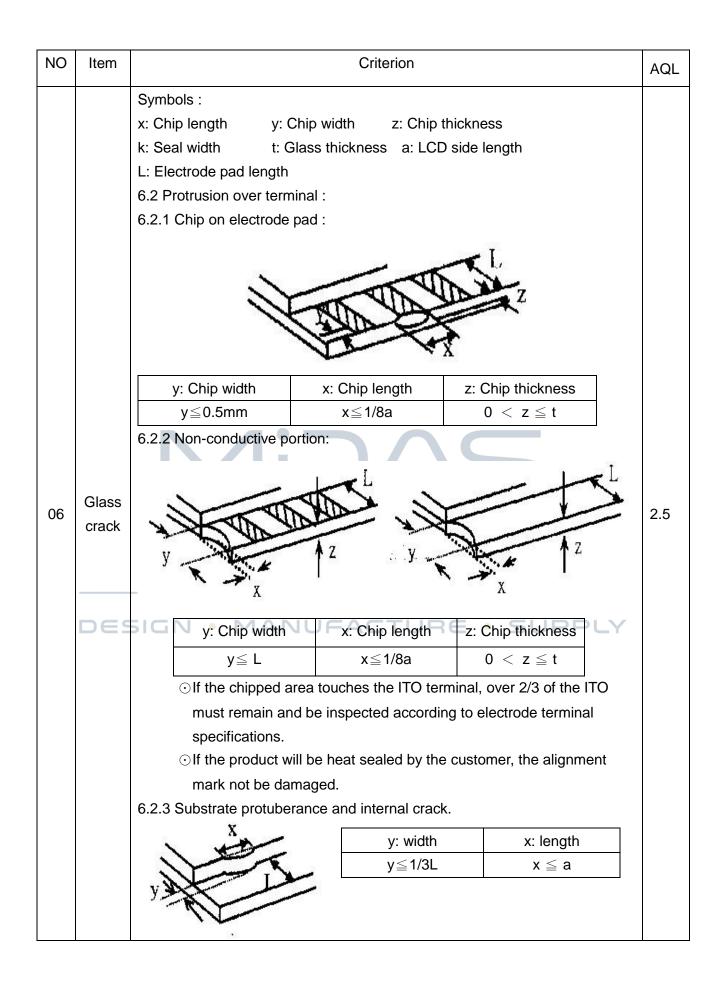
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

# Inspection specification

NO	Item		Criterion		AQL	
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character , dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>				
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>				
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As follow $\Phi = (x + y) / 2$ $\downarrow \qquad \qquad$		Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size $\Phi$ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5	

NO	Item		Criterion		AQL
05	Scratches	Follow NO.3 LCD black	spots, white spots, cont	tamination	
05	Scratches	Symbols Define: x: Chip length y: 0 k: Seal width t: 0 L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur x z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	Chip width z: Chip t Glass thickness a: LCD	thickness b side length panels: x: Chip length $x \le 1/8a$	2.5
		$\hline z: Chip thickness \\ Z \leq 1/2t$	y: Chip width Not over viewing area	<b>y</b> x: Chip length $x \le 1/8a$	
		$1/2t < z \leq 2t$	Not exceed 1/3k	x≦1/8a	
		$\odot$ If there are 2 or more	chips, x is the total leng	th of each chip.	



NO	Item	Criterion			
07	Cracked glass	The LCD with extensive crack is not acceptable.			
	Backlight elements	8.1 Illumination source flickers when lit.			
08		8.2 Spots or scratched that appear when lit must be judged.			
		Using LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65		
	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints,			
09		stains or other contamination.			
		9.2 Bezel must comply with job specifications.	0.65		
		10.1 COB seal may not have pinholes larger than 0.2mm or			
		contamination.	2.5		
		10.2 COB seal surface may not have pinholes through to the IC.			
		10.3 The height of the COB should not exceed the height	2.5		
	PCB · COB	indicated in the assembly diagram.	0.65		
		10.4 There may not be more than 2mm of sealant outside the			
		seal area on the PCB. And there should be no more than three places.	2.5		
		10.5 No oxidation or contamination PCB terminals.			
10		10.6 Parts on PCB must be the same as on the production			
		characteristic chart. There should be no wrong parts,	2.5 0.65		
		missing parts or excess parts.	0100		
	DESIGN	10.7 The jumper on the PCB should conform to the product characteristic chart.	Y		
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	0.65		
		screw hold pad, make sure it is smoothed down.			
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5		
		<b>V</b>	2.5		
		X * Y<=2mm2			
	Soldering	11.1 No un-melted solder paste may be present on the PCB.	2.5		
11		11.2 No cold solder joints, missing solder connections, oxidation	2.5		
		or icicle.			
		11.3 No residue or solder balls on PCB.			
		11.4 No short circuits in components on PCB.	0.65		

NO	Item	Criterion	AQL	
NO 12	Item General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> </ul>	AQL 2.5 0.65 2.5 2.5 2.5 2.5 2.5	
		<ul><li>12.7 Sealant on top of the ITO circuit has not hardened.</li><li>12.8 Pin type must match type in specification sheet.</li></ul>	0.65 0.65	
		<ul><li>12.9 LCD pin loose or missing pins.</li><li>12.10 Product packaging must the same as specified on packaging specification sheet.</li></ul>		
		<ul> <li>packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> <li>12.12 Visual defect outside of VA is not considered to be rejection.</li> </ul>	0.65	

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#### **Precautions in use of LCD Modules**

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Midas have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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### **Material List of Components for RoHs**

- 1. Midas hereby declares that all of or part of products (with the mark
  - "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited	100	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm

Above limited value is set up according to RoHS.

- 2. Process for RoHS requirement : (only for RoHS inspection)
  - (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C; Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

#### **Recommendable Storage**

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.